

Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

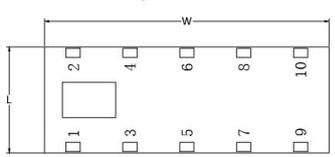
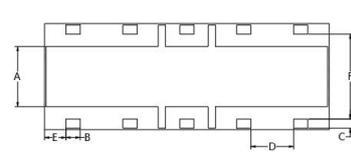
NO.	Specification					
		LPF1	LPF2	LPF3	LPF4	LPF5
1	Frequency range (MHz)	225~330	330~480	480~700	700~1100	1100~1800
2	Insertion Loss (dB) @25°C	1.3	1.3	1.3	1.3	1.3
3	Ripple (dB)	1.0	1.0	1.0	1.0	1.0
4	VSWR (In BW)	12	12	12	12	12
5	Impedance (Ω)	50	50	50	50	50
6	Attenuation (dB)	2-d Harm Rej	50	50	50	50
		3-d Harm Rej	50	50	50	50
Operating & Storage Condition (Component)						
Operation Temperature Range: -40°C ~ +85°C						
Storage Temperature Range: -40°C~ +85°C						
Storage Condition before Soldering (Included packaging material)						
Storage Temperature Range: +5 ~ +40 °C						
Humidity: 30 to 70% relative humidity						

Construction

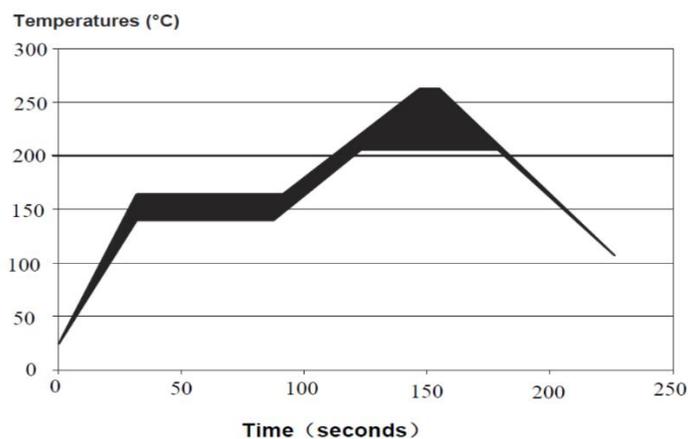


PIN	Connection	PIN	Connection
1	LPF1 input Port	2	LPF1 output Port
3	LPF2 input Port	4	LPF2 output Port
5	LPF3 input Port	6	LPF3 output Port
7	LPF4 input Port	8	LPF4 output Port
9	LPF5 input Port	10	LPF5 output Port

Dimensions

Figure	Symbol	Dimension (mm)
<p style="text-align: center;">Top View</p>  <p style="text-align: center;">Side View</p>  <p style="text-align: center;">Bottom View</p> 	L	6.00 ± 0.20
	W	16.00± 0.20
	T	1.80± 0.20
	A	3.40± 0.10
	B	0.80 ± 0.10
	C	0.60 ± 0.10
	D	2.40± 0.10
	E	1.20± 0.10
	F	4.80± 0.10

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12